

AGENDA

09:00 - 10:00	등록 및 데모부스 관람	
10:00 - 10:10	Opening Speech	김준환 대표이사, Siemens EDA Korea
10:10 - 10:50	Siemens EDA Keynote Speech : Enabling Imagination - A New Era of System Design	Mike Ellow, CEO, Siemens EDA Silicon Systems
10:50 - 11:15	Invited Keynote Speech : Samsung Foundry Advanced Technology and Design Platform Readiness	이성재 상무, 삼성 파운드리
11:15 - 11:40	Invited Keynote Speech : 반도체 설계에서의 CI/CD, Shift-Left	이상현 연구위원, LG전자
11:40 - 13:00	점심식사 및 데모부스 관람	

Technical Sessions	Track 1 AI EDA Tools	Track 2 Design for Power	Track 3 Advanced Mega Chip	Track 4 3D IC	Track 5 Board Systems
13:00 - 13:30	How AI is changing every aspect of EDA Jeff Dyck, Siemens EDA	Aprisa - Full RTL2GDSII Solution with AI Functionality Alpesh Kothari, Siemens EDA	Catapult HLS : Accelerating Neural Network Design at BlueDot for Better Visual Quality 이웅원, BlueDot 정안선, Siemens EDA	Innovator3D IC - comprehensive multiphysics cockpit for 3D IC design 김경록, Siemens EDA	Next Generation Electronic Systems Design 박성초, Siemens EDA
13:30 - 14:00	Introducing Smart Verification: Unleashing the Potential of AI Within Functional Verification Darron May, Siemens EDA	Changing the dynamics with physical-aware RTL power analysis Mohammed Fahad, Siemens EDA	Defect modeling based on actual defect in Samsung Foundry through UDFM and diagnosis flow improvement 박재석, Samsung Electronics	Using XPD to efficiently complete advanced package and daisy chain design 노상목, Siemens EDA	Shift-Left DFM: Enhancing Product Quality and Reducing Costs through Early and Automated Manufacturing Verification 임재한, Samsung Electronics 이원재, Siemens EDA
14:00 - 14:30	Faster PV closure with ML-enhanced debug in Calibre 서요한, Siemens EDA	mPower: First class EMIR analysis for improving design productivity 김세홍, Siemens EDA	Understanding Power and Dynamic IR Drop for DFT Patterns Pre-Silicon Using Veloce Amir Attarha, Siemens EDA Robert Serphillips, Siemens EDA	Case study of using Siemens EDA 3D IC flow at Qualitas 이승호, Qualitas Semiconductor 박상욱, Siemens EDA	Stackup planning for signal integrity using Hyperlynx & Z-Planner 장성혁, Siemens EDA
14:30 - 14:50	커피브레이크 및 데모부스 관람				
14:50 - 15:20	Supercharged high precision Custom IC Verification with AI-accelerated Solido Simulation Suite Pradeep Thiagarajan, Siemens EDA	Track 2 Accelerated System Design Siemens EDA solution for Smart Vehicles Lincoln Lee, Siemens EDA	Marker based P2PCD: Easy efficient verification for P2P/CD measurements at desired layout points using Calibre PERC 김민선, LG Electronics 변선수, Siemens EDA	Tessent Multi-Die for 2.5D and 3D IC designs 유영준, Siemens EDA	Design Reuse Flow Using Self Managed Block at LG Energy Solutions 우가영, LG Energy Solutions 이수영, Siemens EDA
15:20 - 15:50	Accelerate SoC tapeout schedules with production-ready IP & library views from AI-powered Solido Characterization Suite and Solido IP Validation Wei-Lii Tan, Siemens EDA	Enabling a new era of software shift-left with Veloce CS 변용기, Siemens EDA	Avery Verification IP delivers Accelerated Confidence from multi-die chip to datacenter software – UCIe, PCIe, CXL, VICS 방실이, Siemens EDA	Using Calibre 3DThermal to address thermal effects in 3DIC 이훈구, Siemens EDA	Build complete R&D digital thread through Xpedition EDM 김병근, Siemens EDA
15:50 - 16:20	경품 추첨 및 맺음말				